

SL56A SCHOTTKY RECTIFIER

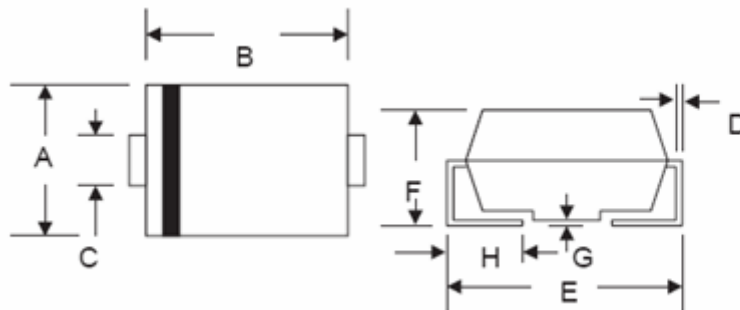
Applications:

- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

Features:

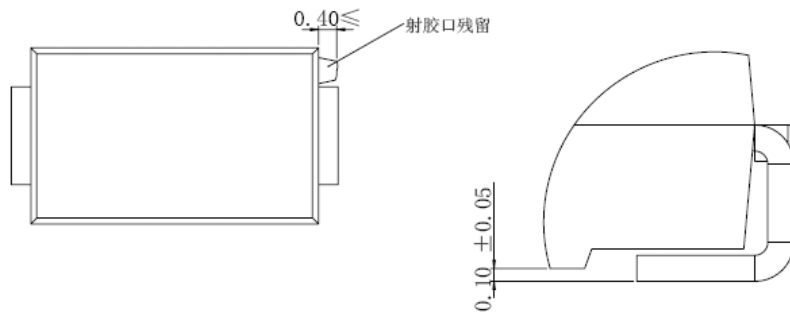
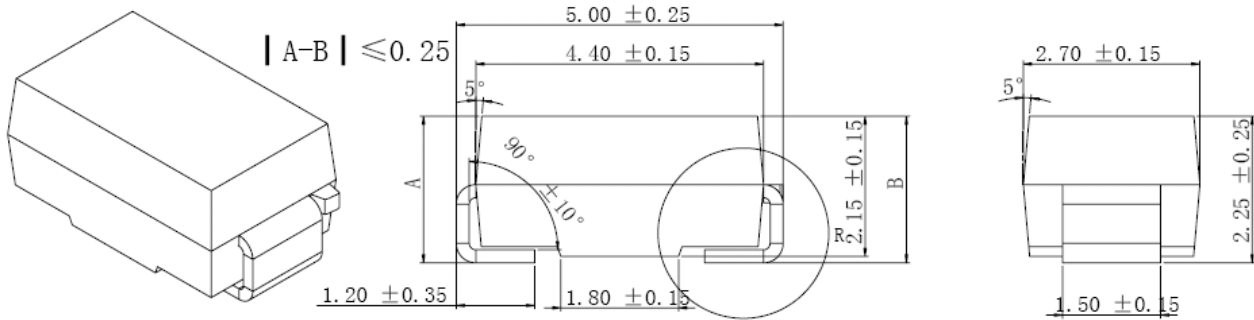
- Schottky Barrier Chip
- Guard Ring Die Construction for Transient Protection
- High Current Capability
- Low Power Loss, High Efficiency
- High Surge Current Capability
- For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Applications
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Mechanical Dimensions (In mm / Inches)



SMA/DO-214AC				
Dim	Min	Max	Min	Max
A	2.50	2.90	0.098	0.114
B	4.00	4.60	0.157	0.181
C	1.40	1.60	0.055	0.063
D	0.152	0.305	0.006	0.012
E	4.80	5.28	0.189	0.208
F	2.00	2.44	0.079	0.096
G	0.051	0.203	0.002	0.008
H	0.76	1.52	0.030	0.060
	In mm		In inch	

OPTION 1



OPTION 2(JK)

SMA



Marking Diagram:

Where XXXXX is YYWWL



- SL = Device Type
- 5 = Forward Current (5A)
- 6 = Reverse Voltage (60V)
- A = Package type
- YY = Year
- WW = Week
- L = Lot Number

Cautions : Molding resin
Epoxy resin UL:94V-0

Ordering Information:

Device	Package	Shipping
SL56A	SMA (Pb-Free)	5000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification.

Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Peak Inverse Voltage	V_{RWM}	-	60	V
Average Forward Current	$I_{F(AV)}$	50% duty cycle @ $T_C = 120^\circ C$ rectangular wave form	5	A
Peak One Cycle Non-Repetitive Surge Current	I_{FSM}	8.3 ms, half Sine pulse	80	A



Electrical Characteristics:

Characteristics	Symbol	Condition	Max.	Units
Forward Voltage Drop	V_{F1}	@ 5A, Pulse, $T_J = 25^\circ\text{C}$	0.6	V
Reverse Current	I_{R1}	@ $V_R = \text{rated VR}$ $T_J = 25^\circ\text{C}$	0.22	mA
Typical Junction Capacitance	C_j	@ $V_R = 4.0\text{ V}$, $T_c = 25^\circ\text{C}$ $f_{\text{SIG}} = 1\text{MHz}$	200	pF

* Pulse Width < 300 μs , Duty Cycle <2%

Thermal-Mechanical Specifications:

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	T_J	-	-55 to +150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-	-55 to +150	$^\circ\text{C}$
Maximum Thermal Resistance Junction to Lead	$R_{\theta\text{JL}}$	DC operation	20	$^\circ\text{C/W}$
Maximum Thermal Resistance Junction to Ambient	$R_{\theta\text{JA}}$	DC operation	150	$^\circ\text{C/W}$
Approximate Weight	wt	-	0.11	g
Case Style	SMA			

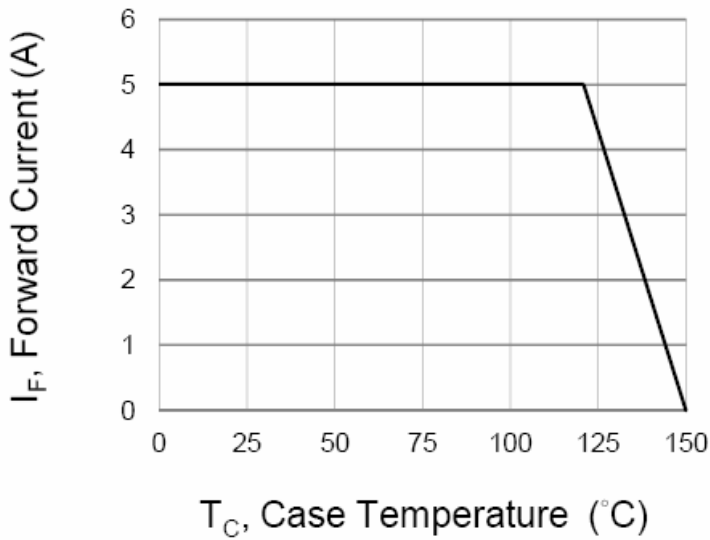


Fig.1-Forward Current Derating Curve

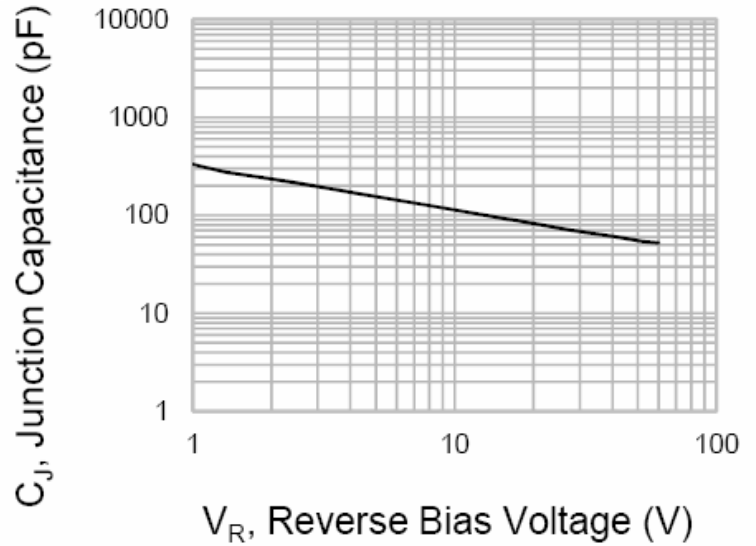


Fig.2-Typical Junction Capacitance

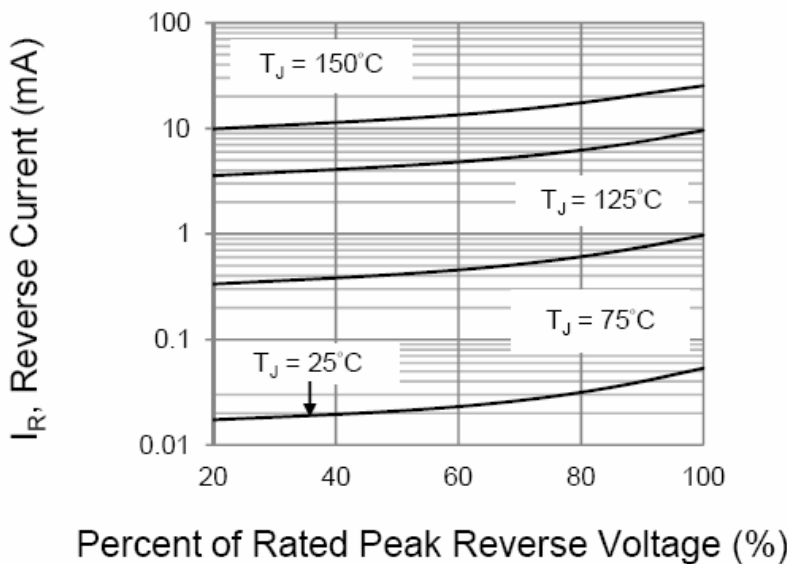


Fig.3-Typical Reverse Characteristics

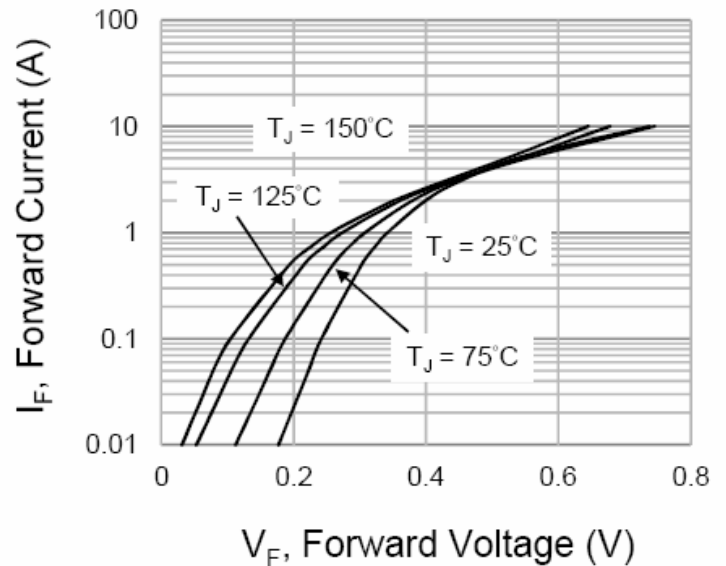


Fig.4-Typical Forward Voltage Characteristics



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